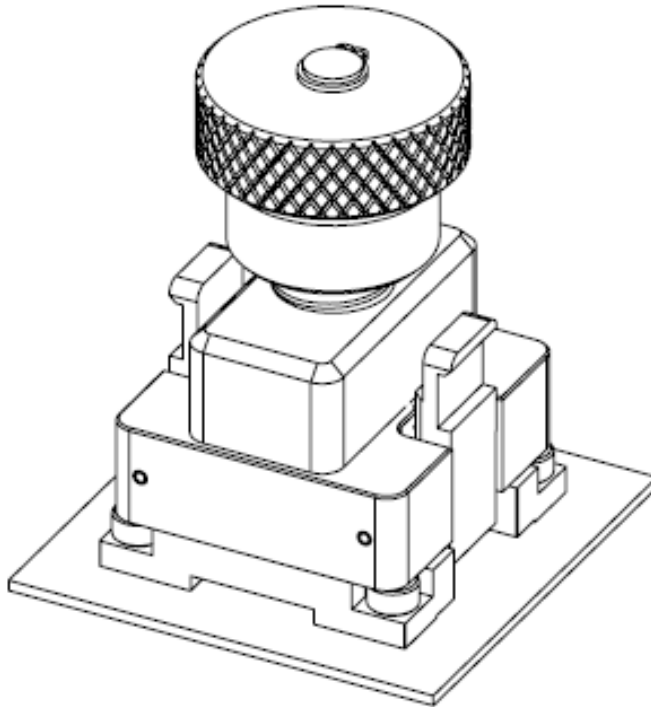
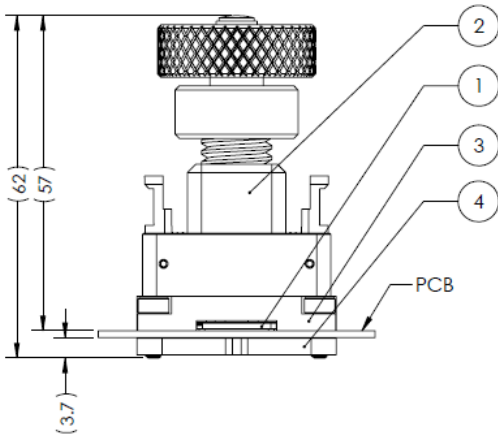
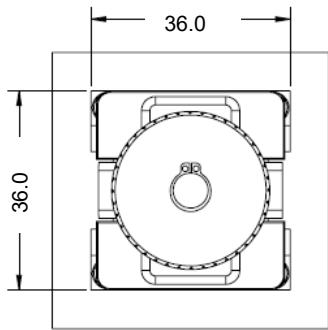
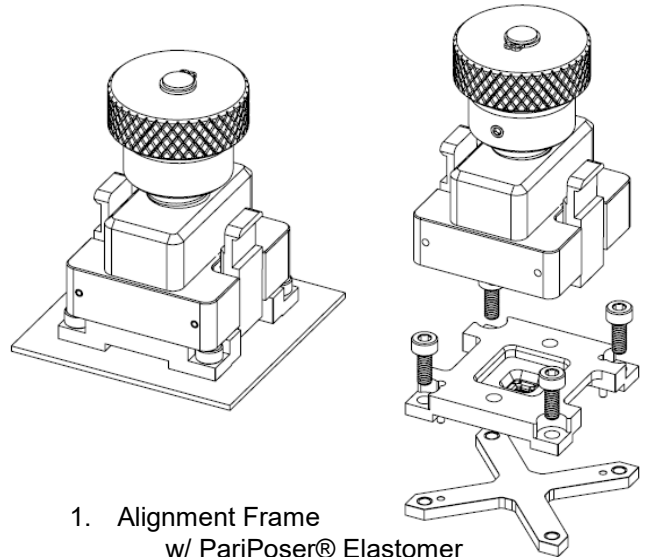


Double Latch Socket Assembly [F15]





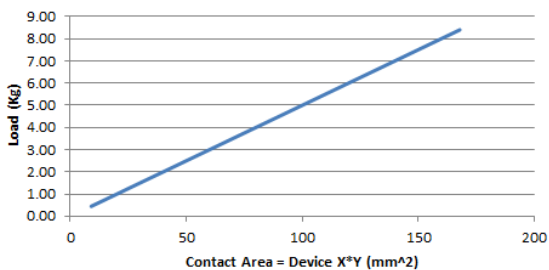
Double Latch Socket Option 1



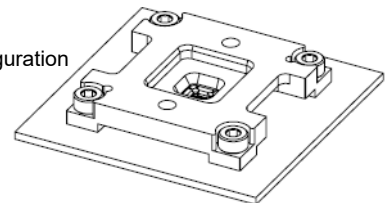
1. Alignment Frame
w/ PariPoser® Elastomer
2. Load Clamp Cover
3. Base Plate
4. Support Plate

Double Latch Socket (Option 1)

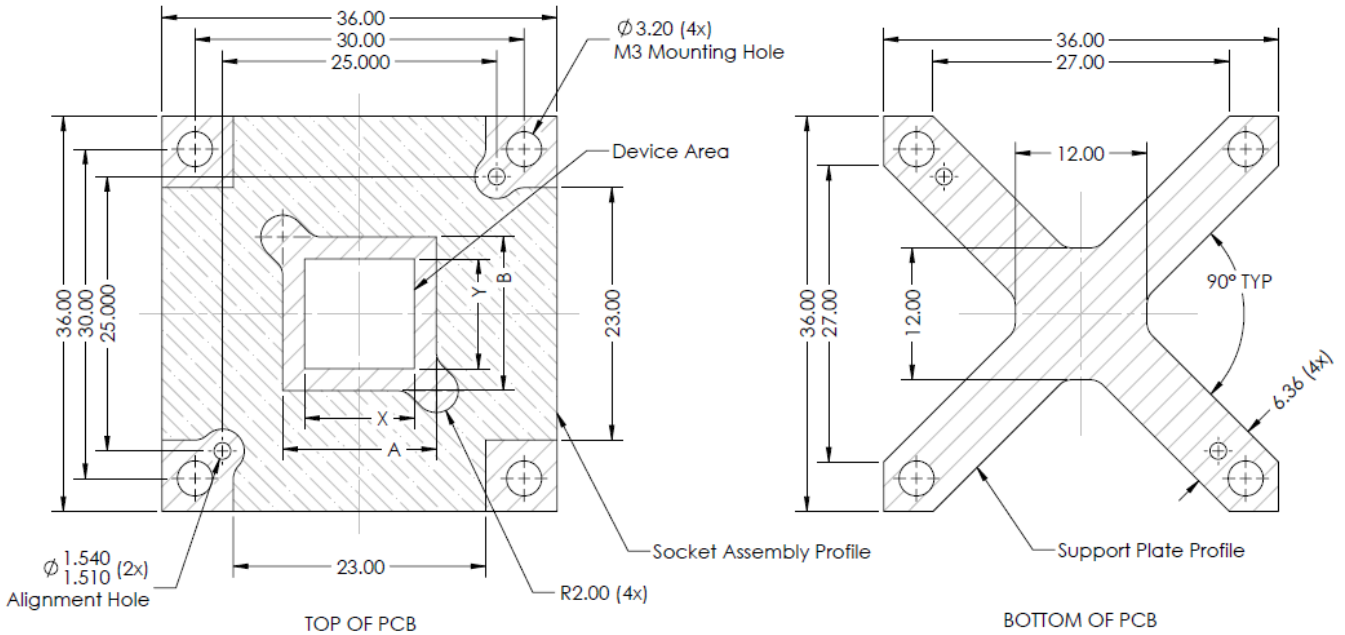
- Handler Test Socket
- Manually Loadable with Latching Clamp Cover
- Can accommodate short PCB components within the socket clamp area
- Device Sizes: **3x3mm** to **12x14mm**
- 0.1 to 1.27mm Pitch Applications
- Compatible with most devices (e.g. LGA, QFN, BGA, Copper Pillar)
- Nominal Clamp Load for 12x14mm LGA: **8.4 kg** [18.5 lbs.]
- Clamp Load Adjustable, Initial Factory Preset Based on Application
- Customizable Features:
 - Alignment frame can be modified to include RF trace clearance.



Handler Configuration



Double Latch Socket – Standard Footprint Drawing Option 1A



- Height over PCB: 0.00mm (Component Keep Out Zone)
- Height over PCB: 1.80mm

Label	Dimension	Tolerance
X	Nominal Device X Dimension	
Y	Nominal Device Y Dimension	
A	X + 4.00 (mm)	+/-0.025
B	Y + 4.00 (mm)	+/-0.025

X.	± 1.0
X.X	± 0.25
X.XX	± 0.10
X.XXX	± 0.025

Tolerances on dimensions shown may vary by device pitch.

Double Latch (Option 1A)

Allows short components to be close to the device. Footprint profile varies per device.

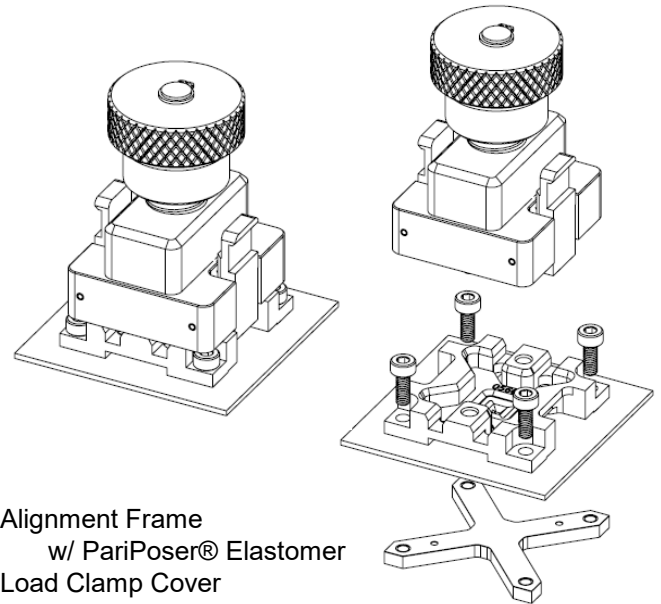
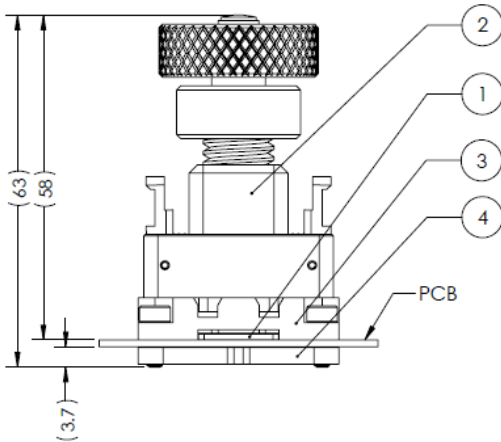
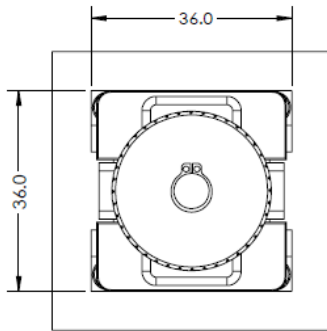
Recommended Device Size Range:

- X = 3mm to 12mm
- Y = 3mm to 14mm
- Device sizes outside the recommended size range may require a custom socket footprint.

Recommended PCB Attributes:

- No soldermask within device area
- ENIG or Hard Gold plating on pads

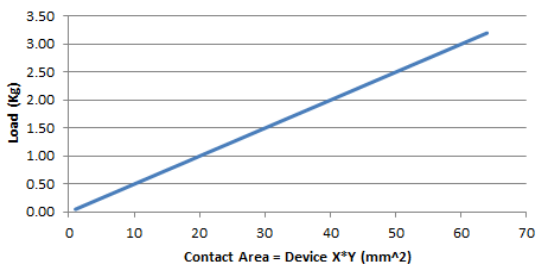
Double Latch Socket Option 2 – Small Device



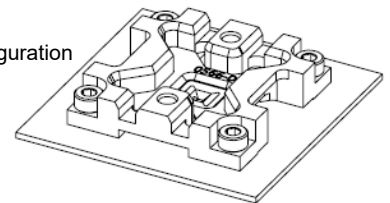
1. Alignment Frame
w/ PariPoser® Elastomer
2. Load Clamp Cover
3. Base Plate
4. Support Plate

Double Latch Socket (Option 2)

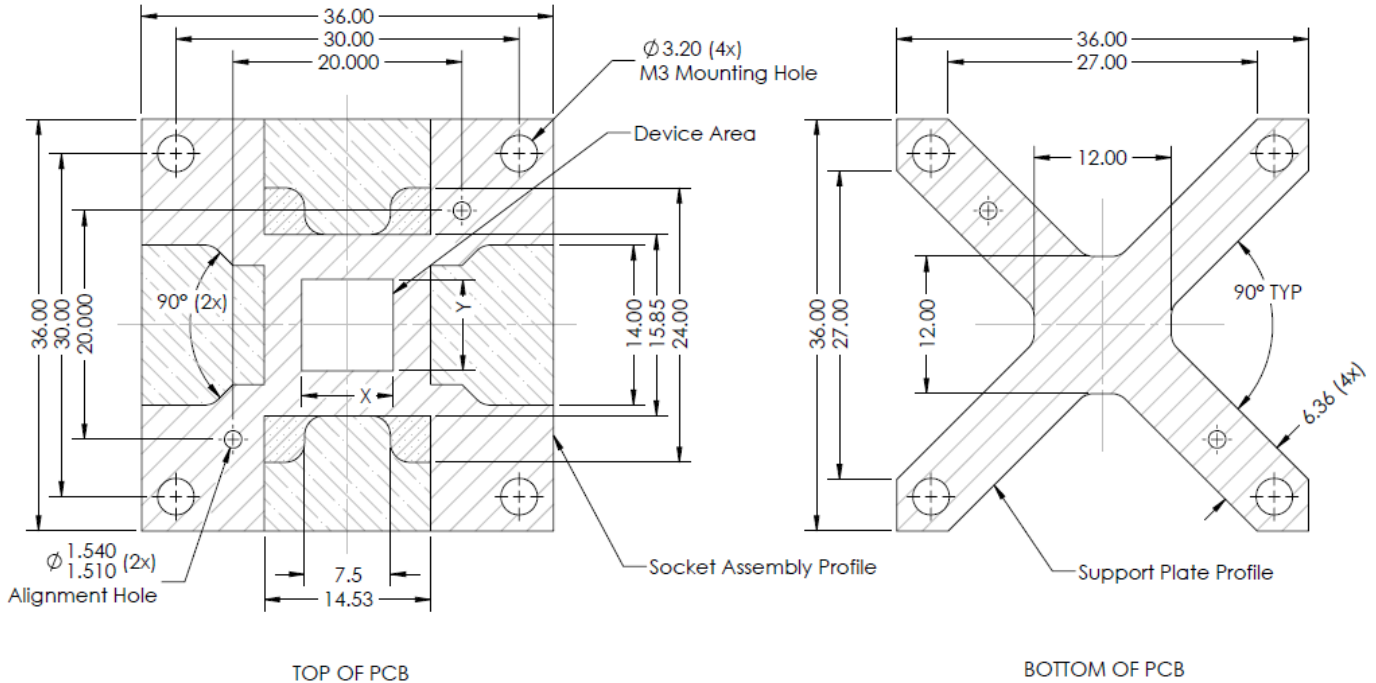
- Handler Test Socket
- Manually Loadable with Latching Clamp Cover
- Can accommodate short PCB components to be within the socket clamp area
- Device Sizes: **1x1mm to 8x8mm**
- 0.1 to 1.27mm Pitch Applications
- Compatible with most devices (e.g. LGA, QFN, BGA, Copper Pillar)
- Nominal Clamp Load for 8x8mm LGA: **3.2 kg** [7.1 lbs.]
- Clamp Load Adjustable, Initial Factory Preset Based on Application
- Easily replaceable alignment frame
- Customizable Features:
 - Alignment frame can be modified to include RF trace clearance.




Handler Configuration



Double Latch Socket – Standard Footprint Drawing Option 2 (Small Device)



	Height over PCB: 0.00mm (Component Keep Out Zone)
	Height over PCB: 1.00mm
	Height over PCB: 1.80mm

X.	± 1.0
X.X	± 0.25
X.XX	± 0.10
X.XXX	± 0.025

Tolerances on dimensions shown may vary by device pitch.

Double Latch (Option 2)

Allows the alignment and testing of small device sizes, or fine pitch devices.

Recommended Device Size Range:

- X = 1mm to 8mm
- Y = 1mm to 8mm
- Device sizes outside the recommended device range may require a custom socket footprint.

Recommended PCB Attributes:

- No soldermask within device area
- ENIG or Hard Gold plating on pads

